

Special Issue

Advanced Technologies in Electronic Packaging

Message from the Guest Editors

Electronic devices are widely applied in daily life, the environment, life sciences, industry fields, etc., including semiconductor devices, power devices, MEMS devices, optoelectronic devices, and so on. Electronic packaging is a key process for the fabrication of devices, and its functions contain mechanical protection, electrical interconnection, performance enhancement, and heat dissipation. In order to enhance the performances and reliability of electronic devices, some advanced technologies have been proposed and developed in electronic packaging, including advanced packaging mechanisms, packaging materials, packaging structures, packaging technologies, and evaluation methods, and can be optimized by means of theoretical analysis, simulation, and experiments. This Special Issue seeks to showcase research papers and review articles discussing recent developments and applications of advanced electronic packaging, including novel packaging materials, reliable packaging structures, advanced packaging technologies, and new applications.

Guest Editors

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Deadline for manuscript submissions

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